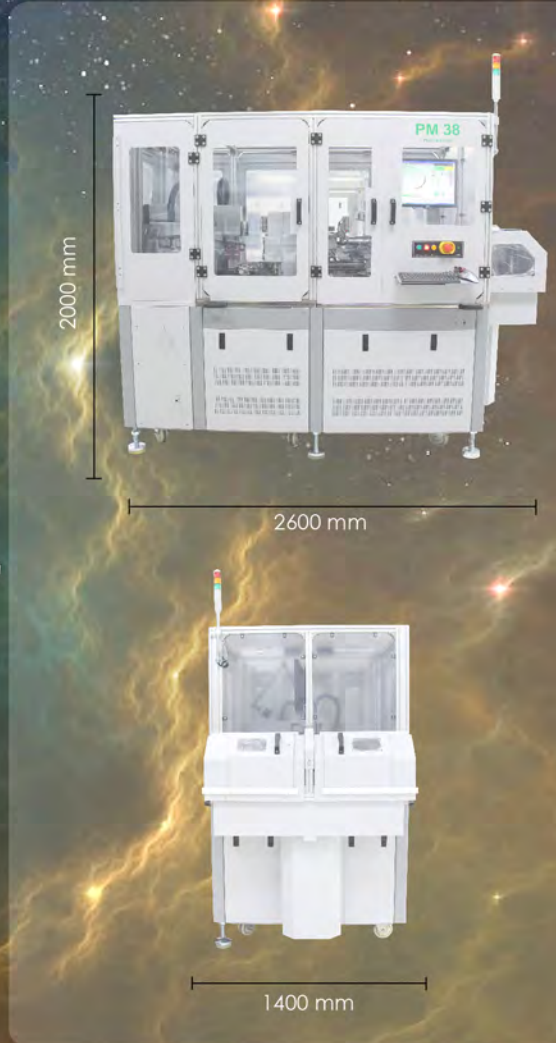


PM38



We provide fully automatic, high speed, intelligent Die Sorting Handler. Featuring state of the art vision technology. This handler utilizes cutting edge technologies in robotic motion control and as such comes packaged with a user friendly interface, providing a truly robust solution.



Outstanding FEATURES

- **High speed** - UPH up to 18,000 with non-flip operation.
- **Flexibility** - Flexible to integrate sub modules to perform various task such as testing, laser marking and etc.
- **Intelligent sorting** - Sorting out good/NG die with map file collaboration.
- **Auto-replacer** - Automatic die replacement for in-pocket vision.



SPECIFICATIONS

System Capabilities

Package Type

- QFN, WLCSP, MEMS microphone

Package Size

- 1.0 mm ~ 4.0 mm

Spring UPH

- 15,000 (Flip)
- 18,000 (Non Flip)

| | |
|--------------------|-------------|
| MTBA | > 60 mins |
| MTBF | > 200 hours |
| Conversion Time | < 60 mins |
| Placement Accuracy | < 0.025 mm |

Input Options

- 6", 8" Wafer Size

Output Options

- Tape & Reel (8 mm/ 12 mm Tape Width)
- JEDEC tray

Ejection Table

- Programmable Tape Expansion

Flipper

- Capable for Flip and Non-Flip Operation

User Interface

- Window base with GUI
- Full system diagnostic capabilities

Facilities

Dimension & Weight

- 2600(L) mm x 1400(W) mm x 2000(H) mm
- 1200 kg

Incoming Power

- 3 Phase 208 VAC 50/60 Hz

Power Consumption

- 20 Amps

Air Supply

- CDA Min. 5 bar / 65 psi x 2

Warranty

Equipment (non-consumable parts)

- 1 year

Vision Capabilities

Vision Inspection

- Bottom Package For Positioning, Package Location, Package size
- Top Package Vision Inspection For Package and Marking
- 5 Sided Package Inspection
- In-Pocket Vision Inspection
- Post Seal Vision Inspection

2D Pad Measurement

- Size (Length & Width)
- Pitch
- True Position
- Sawn Edge Offset
- Sawn Edge Parallelism
- Device Size (Length & Width)
- Edge & Corner Chipping

3D Measurement

- Coplanarity

Active Die Inspection

- Contamination
- Foreign Material

Back Side Inspection

- Mark & Orientation
- Foreign Material in Pocket

Post Seal Inspection

- Sealing Quality (Broken / Missing / Uneven Sealing)
- Device Quality
- Orientation

GR&R

- < 10%

Vision Accuracy

- ± 0.010 mm*

*Depending on package size